

UNISONIC TECHNOLOGIES CO., LTD

10NM90 **Preliminary** Power MOSFET

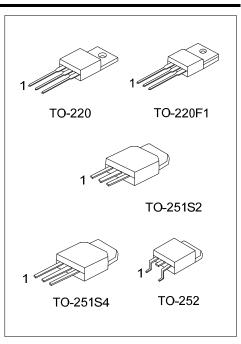
10A, 900V N-CHANNEL SUPER-JUNCTION MOSFET

DESCRIPTION

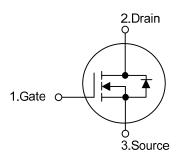
The UTC 10NM90 is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at DC-DC, AC-DC converters for power applications.

FEATURES

- * $R_{DS(ON)}$ < 1.00 @ V_{GS} = 10V, I_{D} = 5.0A
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness



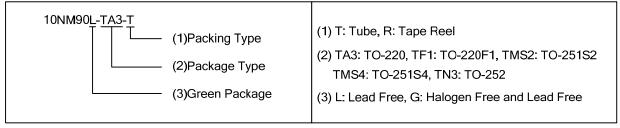
SYMBOL



ORDERING INFORMATION

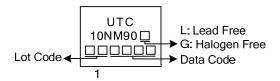
Ordering Number		Daakaga	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
10NM90L-TA3-T	10NM90G-TA3-T	TO-220	G	D	S	Tube	
10NM90L-TF1-T	10NM90G-TF1-T	TO-220F1	G	D	S	Tube	
10NM90L-TMS2-T	10NM90G-TMS2-T	TO-251S2	G	D	S	Tube	
10NM90L-TMS4-T	10NM90G-TMS4-T	TO-251S4	G	D	S	Tube	
10NM90L-TN3-R	10NM90G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



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MARKING



■ ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{ extsf{DSS}}$	900	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current	Continuous	I_{D}	10	Α
Pulsed Drain Current	Pulsed (Note 2)	I_{DM}	40	Α
Avalanche Current (Note 2)		I_{AR}	2.4	Α
Single Pulsed Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	458	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	2.24	V/ns
	TO-220		158	W
Pawer Dissination	TO-220F1	В	50	W
Power Dissipation	TO-25S2/TO-251S4	P_D	70	10/
	TO-252		70	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

- Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

 Absolute maximum ratings are stress ratings only and functional device operation is not implied.
 - 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
 - 3. L = 159mH, I_{AS} = 2.4A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C.
 - 4. $I_{SD} \le 10A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$.

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-220/TO-220F1		62.5	°C/W
	TO-25S2/TO-251S4 TO-252	θ_{JA}	110	°C/W
Junction to Case	TO-220		0.79	°C/W
	TO-220F1		2.5	°C/W
	TO-25S2/TO-251S4 TO-252	θ _{JC}	1.79	°C/W

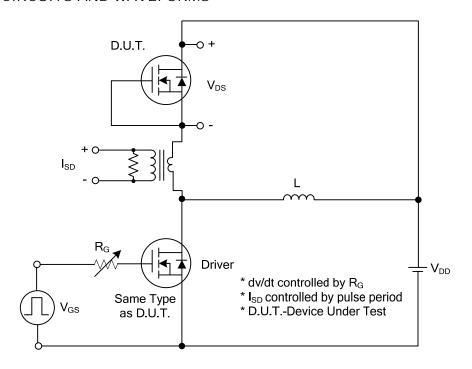
■ ELECTRICAL CHARACTERISTICS (T_J=25°C, unless otherwise specified)

DADAMETED		SYMBOL	TEST CONDITIONS	MIN	TVD	MAX	LINIT	
PARAMETER		STIVIBUL	TEST CONDITIONS	IVIIIN	ITP	IVIAA	UNIT	
OFF CHARACTERISTICS		l., a., a.						
Drain-Source Breakdown Voltage		BV _{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	900			V	
Drain-Source Leakage Current		I_{DSS}	$V_{DS} = 900V, V_{GS} = 0V$			10	μA	
Gate-Source Leakage Current	Forward	- I _{GSS}	$V_{GS} = 30V$, $V_{DS} = 0V$			100	nA	
	Reverse		$V_{GS} = -30V, V_{DS} = 0V$			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$			4.5	V	
Static Drain-Source On-State Resistance		R _{DS(ON)}	$V_{GS} = 10V, I_D = 5.0A$			1.0	Ω	
DYNAMIC CHARACTERISTICS								
Input Capacitance		C_{ISS}			840		pF	
Output Capacitance		Coss	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		240		pF	
Reverse Transfer Capacitance		C_{RSS}	1		4		pF	
SWITCHING CHARACTERISTICS								
Total Gate Charge (Note 1)		Q_G	V _{DS} =50V, I _D =1.3A, I _G =100μA		55		nC	
Gate to Source Charge		Q_GS	V _{GS} =10V (Note 1,2)		5.5		nC	
Gate to Drain Charge		Q_GD	VGS=10V (Note 1,2)		17		nC	
Turn-ON Delay Time (Note 1)		$t_{D(ON)}$			50		nS	
Rise Time		t_{R}	$V_{DD} = 30V$, $I_D = 0.5A$, $R_G = 25\Omega$,		95		nS	
Turn-OFF Delay Time		$t_{D(OFF)}$	V _{GS} =10V (Note 1,2)		365		nS	
Fall-Time		t _F	7		70		nS	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuous C	urrent	Is				10	Α	
Maximum Body-Diode Pulsed Current		I _{SM}				40	Α	
Drain-Source Diode Forward Voltage (Note 1)		V_{SD}	I _S =10A, V _{GS} =0V			1.4	V	
Body Diode Reverse Recovery Time (Note 1)		t _{rr}	I _S =10A, V _{GS} =0V,		580		nS	
Body Diode Reverse Recovery Charge		Q _{rr}	dI _F /dt=100A/μs		8.8		μC	

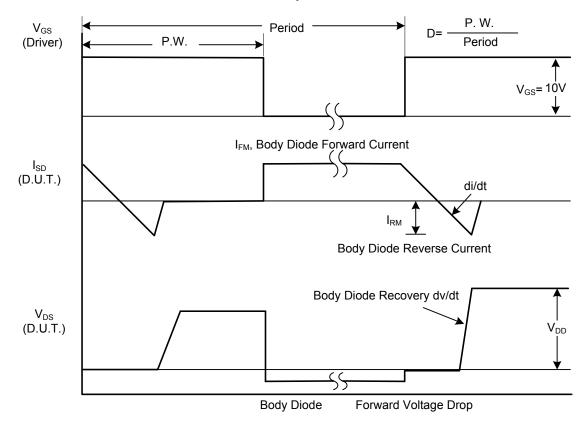
Notes: 1. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%.

^{2.} Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS

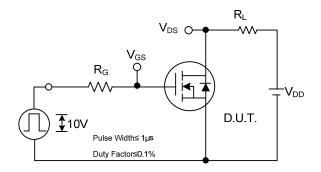


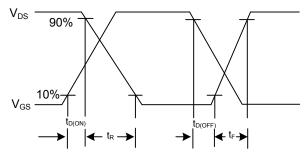
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

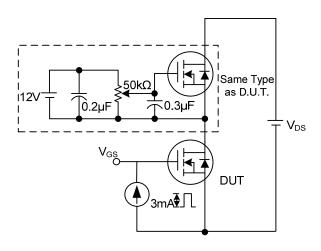
■ TEST CIRCUITS AND WAVEFORMS (Cont.)

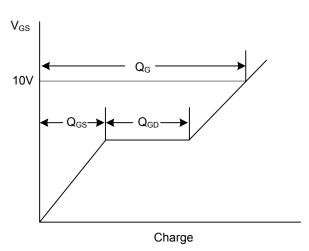




Switching Test Circuit

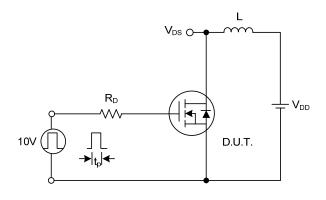
Switching Waveforms

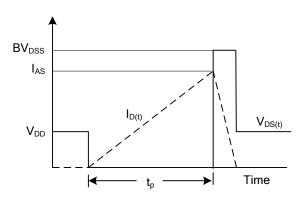




Gate Charge Test Circuit

Gate Charge Waveform





Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

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